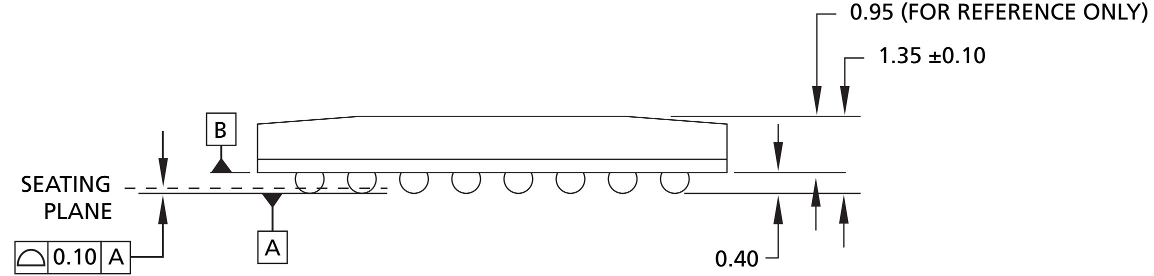
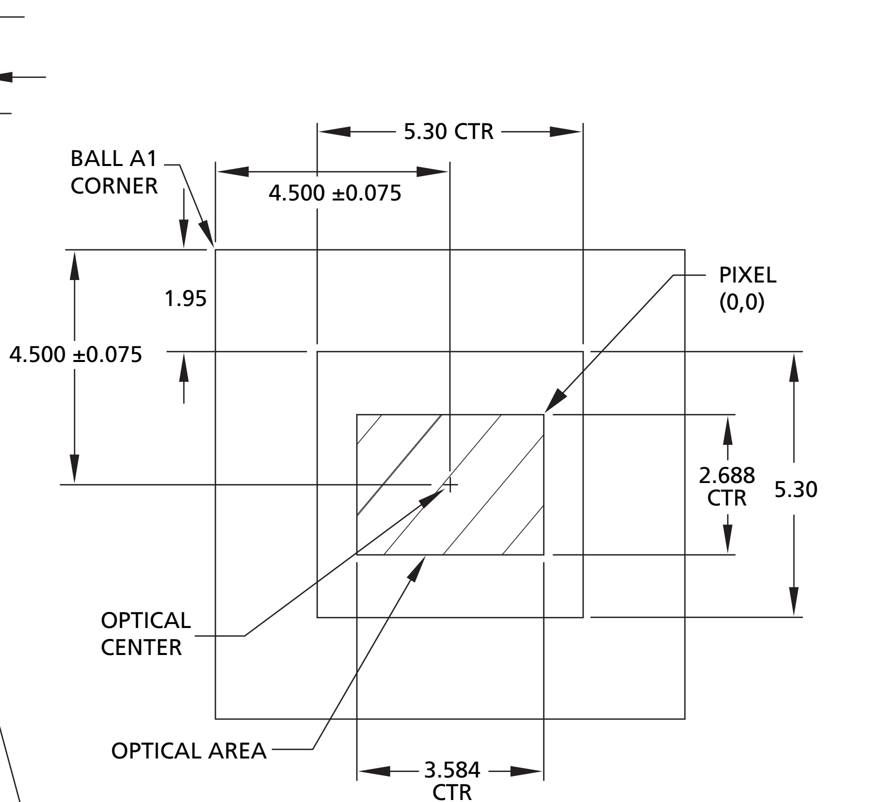
All Dimensions in Millimeters.



52X Ø0.55
DIMENSIONS APPLY TO SOLDER BALLS POST REFLOW. THE PRE-REFLOW DIAMETER IS Ø0.50.
BALL A8
7.00
1.00 TYP
BALL A1
BALL A1 ID
4.50 ±0.05
9.000 ±0.075
7.00
3.50
1.00 TYP
3.50
4.50 ±0.05
9.000 ±0.075

0.175
(FOR REFERENCE ONLY)
0.575 ±0.050
0.375 ±0.050



MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO PACKAGE EDGES: 1°
MAXIMUM TILT OF OPTICAL AREA RELATIVE TO PACKAGE EDGE B 0.3°.
MAXIMUM TILT OF OPTICAL AREA RELATIVE TO TOP OF COVER GLASS: 0.3°.

SOLDER BALL MATERIAL: 62% Sn, 36% Pb, 2% Ag
OR 96.5% Sn, 3% Ag, 0.5% Cu
NON SOLDER MASK DEFINED BALL PADS: Ø 0.40
SUBSTRATE MATERIAL: PLASTIC LAMINATE
ENCAPSULANT: EPOXY
LID MATERIAL: BOROSILICATE GLASS 0.40 THICKNESS
IMAGE SENSOR DIE